OLI3539V.A1-850-A

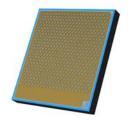
BIDOS® Core











Features:

Chip Technology: GaAs VCSEL

— IR Laser Wavelength: 850 nm

Optical Power Class: 3 W pulsed

— Radiation Profile: Multi Mode

ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Туре	Operational Mode:	Ordering Code	
	$I_F = 4 \text{ A}, T_a = 25^{\circ}\text{C}$		
	$t_p = 100 \mu s, DC = 1\%$		
OLI3539V.A1-850-A	3.3 W	Q65113A1723	

Depending on the mode of operation, these devices emit highly concentrated visible and non-visible light which can be hazardous to the human eye. Products which incorporate these devices must follow the safety precautions given in the "Notes" section.



Maximum Ratings

 $T_a = 25$ °C

Parameter	Symbol		Values
Operation/Solder temperature	Ts	min.	-40 °C
$t_p = 100 \ \mu s; \ DC = 1 \%$		max.	100 °C
Storage temperature	T _{stg}	min.	-40 °C
		max.	100 °C
Forward current	lf	max.	8 A
Pulsed operation; T_p = 100 μ s; DC = 1%; T_S = 25°C			
Forward current	lf	max.	4.5 A
Direct current operation; DC = 100%; Ts = 25°C			
Reverse Voltage	Not designed for reverse operation		
ESD withstand voltage	VESD	max.	2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)			

Note: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.



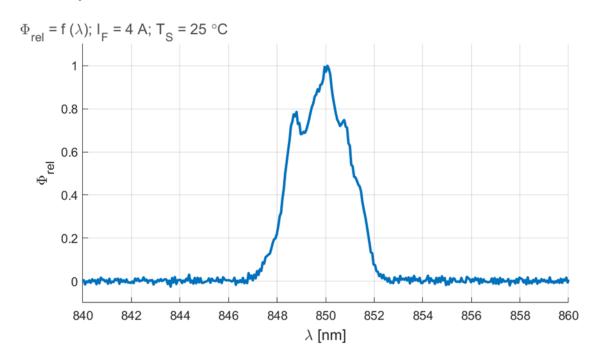
Characteristics

 $T_a = 25$ °C, $I_F = 4$ A; $t_p = 100 \ \mu s$; DC = 1%

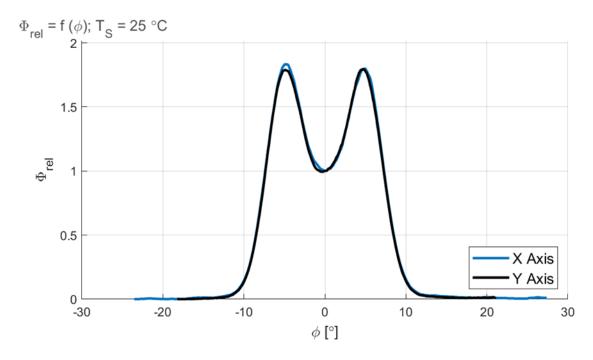
Parameter	Symbol		Values
Forward voltage	VF	typ.	2.1 V
Output power	Φ	typ.	3.3 W
Threshold current	I _{th}	typ.	1.2 A
Slope efficiency	SE	typ.	1.1 W / A
Power conversion efficiency	η	typ.	39 %
Peak wavelength	λ_{peak}	min.	840 nm
		typ.	850 nm
		max.	860 nm
Spectral bandwidth at FWHM (50% of Φ_{max})	λεwhm	typ.	2 nm
Temperature coefficient of wavelength	ТСλ	typ.	0.06 nm /K
Field of view at FWHM (50% of Φ_{max})	φ _X	typ.	15°
	\$ Y	typ.	15°



Relative Spectral Emission 1)

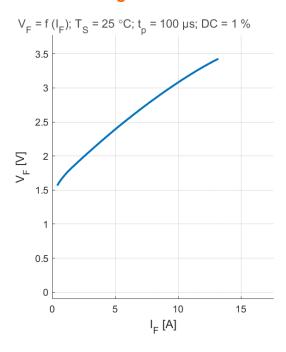


Radiation Characteristics 1)

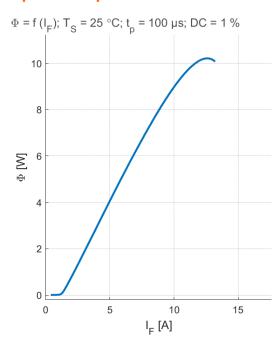




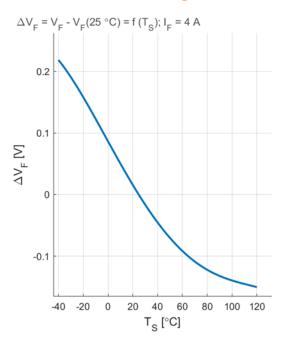
Forward Voltage 1) 2)



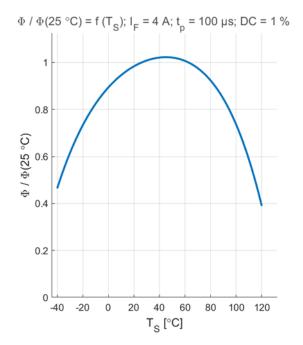
Optical Output Power 1) 2)



Relative Forward Voltage 1)

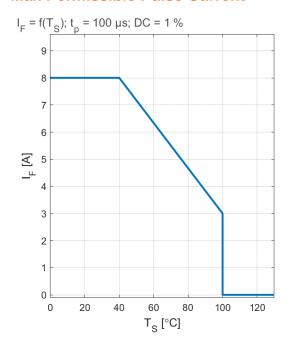


Relative Radiant Power 1)

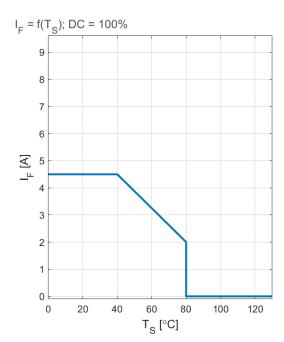




Max Permissible Pulse Current

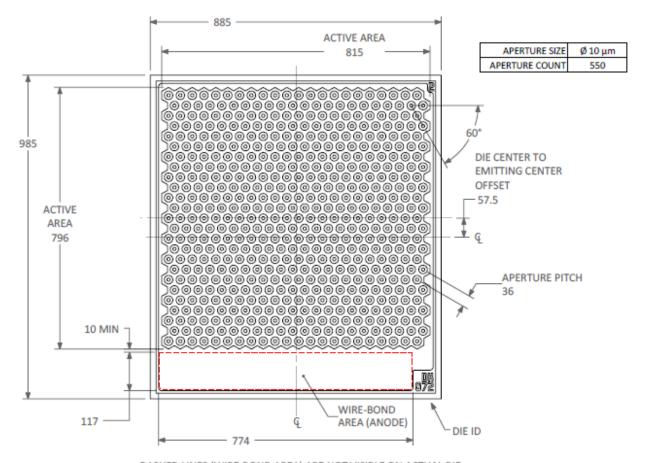


Max Permissible Current

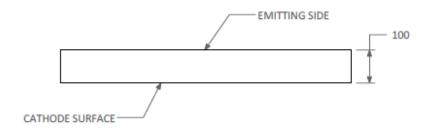




Dimension Drawings 3)



DASHED LINES (WIRE-BOND AREA) ARE NOT VISIBLE ON ACTUAL DIE





Notes

Depending on the mode of operation, these devices emit highly concentrated visible and non-visible light which can be hazardous to the human eye. Products which incorporate these devices must follow the safety precautions given in IEC 60825-1.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

OSRAM OS assumes no liability whatsoever for any use of this document or its content by recipient including, but not limited to, for any design in activities based on this preliminary draft version. OSRAM OS may e.g. decide at its sole discretion to stop developing and/or finalizing the underlying design at any time.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

In case Buyer – or Customer supplied by Buyer– considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordinate the customer-specific request between OSRAM OS and Buyer and/or Customer.



Glossary

- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Testing temperature: $T_a = 25$ °C
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.



Revision History

Version	Date	Change
0.0	November 10 th , 2020	Initiation of preliminary datasheet
1.0	December 11 th , 2020	Release

Published by OSRAM Opto Semiconductors GmbH EU RoHS and China RoHS compliant product Leibnizstraße 4, D-93055 Regensburg www.osram-os.com © All Rights Reserved. 此产品符合欧盟 RoHS 指令的要求;按照中国的相关法规和标准,不含有毒有害物质或元素。

